



FABRICATION NOTES:

1. Material: Six layer, FR4 glass epoxy laminate, 1.6mm +/-10% thick.
Starting Copper Weight: 1/2 oz all layers.
Material to be RoHS compliant.
2. Plated thru holes and the conductive pattern electroplated with 25um min. thick copper. Terminal areas and plated thru holes to be ENIG plated. Soldermask over bare copper.
3. Finished Board to be RoHS Compliant
4. Datum for (x,y) co-ordinate drill files at LLH Corner.
5. Processing tolerances:
 - A. Conductive pattern front to back registration within 0.1mm total.
 - B. Minimum annular ring surrounding holes: 0.05mm
 - C. Finished conductive pattern within 0.05mm of true size.
6. Warp and twist within 1%
7. Dimensions are for the finished part.
8. Solder Mask: Liquid photo imagable solder mask over bare copper (smobc), colour green, both sides using the patterns provided. No mask is permitted on the terminal areas. Soldermask to etch registration within 0.127mm total.
9. Screening: Screen component outlines and nomenclature using indelible white ink on the primary and secondary sides (as required). Nomenclature shall be legible. Screen to etch registration within 0.2mm
10. Electrically Tested 100%
11. Break all sharp edges 0.381mm R max.
12. Manufacturer to add Ident, UL number and Date Code (YY/WW format) in this area as silkscreen on the bottom side.

SIZE	QTY	SYM	PLATED	TOL
0.889	180	+	YES	+/-0.08
0.4	422	X	YES	+/-0.08
1	81	□	YES	+/-0.08
0.25	55	◇	YES	+/-0.08
1.0414	8	⊗	YES	+/-0.08
1.778	2	⊗	YES	+/-0.08
1.524	2	+ ^A	YES	+/-0.08
1.59	4	+ ^B	NO	+/-0.08
1.65	2	+ ^C	NO	+/-0.08
0.15	55	+ ^D	YES	+/-0.08
1.4	2	+ ^E	YES	+/-0.08
1.6	1	+ ^F	NO	+/-0.08
1.8	1	+ ^G	NO	+/-0.08

08-040314a (EVAL-ADuCM320iQSPZ_Rev A) Top Side View

FABRICATION DRAWING